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Patent Application

I hereby certify that this transmittal of the below described document is being deposited with the United States Postal Service in an envelope bearing First Class Postage and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the below date of deposit.

Date of Deposit:	06/13/05	Name of Person Making the Deposit:	KATHERINE RINALDI	Signature of the Person Making the Deposit:	<i>Katherine Rinaldi</i>
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In re Application

Inventor(s): Mike F. Chang, King Owyang, Yueh-Se Ho, Y. Mohammed Kasem, Lixiong Luo and Wei-Bing Chu

Application No.: 09/468,249

Filed: 12/10/99

Title: SEMICONDUCTOR DIE PACKAGE INCLUDING CUP-SHAPED LEADFRAME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

NOTIFICATION OF FILING OF CONTINUATION APPLICATION CLAIMING
BENEFIT OF FILING DATE
(THIS IS NOT A REQUEST FOR A CPA FILING)

☒ Notification is hereby being made of the filing of a continuation application claiming benefit for filing date for this case

☒ concurrently herewith.
☐ on

Please direct all correspondence concerning the above-identified application to the following address:

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Respectfully submitted,

Date:

6/13/2005

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